Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	8942	((438/118,119) or (257/672,673, 678,684,687,780,738,782,783, 784)).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/09/30 09:01
S2	7239	S1 and @ad<"20030313"	US-PGPUB; USPAT	OR	ON	2005/09/30 09:02
S3	2121	S2 and (dispersant or paste or (conduct$3 with particle$1))	US-PGPUB; USPAT	OR	ON	2005/09/30 09:02
S4	1441	S3 and resin	US-PGPUB; USPAT	OR	ON	2005/09/30 09:02
S5	1219	S4 and ((external adj terminal) or (solder))	US-PGPUB; USPAT	OR	ON	2005/09/30 09:03
S6	25	S5 and (interconnect adj pattern)	US-PGPUB; USPAT	OR	ON	2005/09/29 11:17
S7	4	(("6201302") or ("6621172") or ("6625032") or ("6737750")).PN.	USPAT; USOCR	OR	OFF	2005/09/29 11:18
S8	1662	(438/118,119).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/09/30 10:28
S9	1431	S8 and @ad<"20030313"	US-PGPUB; USPAT	OR	ON	2005/09/29 11:36
S10	768	S9 and resin	US-PGPUB; USPAT	OR	ON	2005/09/29 11:37
S11	545	S10 and ((external adj terminal) or (solder))	US-PGPUB; USPAT	OR	ON	2005/09/29 13:44
S12	1662	(438/118,119).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/09/29 13:45
S13	1431	S12 and @ad<"20030313"	US-PGPUB; USPAT	OR	ON	2005/09/29 13:45
S14	768	S13 and resin	US-PGPUB; USPAT	OR	ON	2005/09/29 13:45
S15	545	S14 and ((external adj terminal) or (solder))	US-PGPUB; USPAT	OR	ON	2005/09/29 13:45
S16	268	S15 and (dispersant or paste or (conduct$3 with particle$1))	US-PGPUB; USPAT	OR	ON	2005/09/29 17:20
S17	57	S15 and ((dispersant or paste) and (conduct$3 with particle$1))	US-PGPUB; USPAT	OR	ON	2005/09/29 13:51
S18	7549	(257/672,673,678,684,687,780,738, 782,783,784).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/09/30 09:01
S19	6015	S18 and @ad<"20030313"	US-PGPUB; USPAT	OR	ON	2005/09/30 10:30
S20	1670	S19 and (dispersant or paste or (conduct$3 with particle$1))	US-PGPUB; USPAT	OR	ON	2005/09/30 10:31
S21	1155	S20 and resin	US-PGPUB; USPAT	OR	ON	2005/09/30 10:44

S22	997	S21 and ((external adj terminal) or (solder))	US-PGPUB; USPAT	OR	ON	2005/09/30 09:05
S23	798	S22 and (substrate and chip)	US-PGPUB; USPAT	OR	ON	2005/09/30 13:43
S24	2	S23 and (dispersant with particles)	US-PGPUB; USPAT	OR	ON	2005/09/30 09:08
S25	72	S23 and (paste with particles)	US-PGPUB; USPAT	OR	ON	2005/09/30 09:08
S26	1537	(361/765,777,783).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/09/30 10:30
S27	1346	S26 and @ad<"20030313"	US-PGPUB; USPAT	OR	ON	2005/09/30 10:30
S28	353	S27 and (dispersant or paste or (conduct$3 with particle$1))	US-PGPUB; USPAT	OR	ON	2005/09/30 10:41
S29	422952	(dispersant or paste or (conduct$3 with particle$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:42
S30	356217	S29 and @ad<"20030313"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 11:53
S31	18332	S30 and (substrate and chip)	US-PGPUB; USPAT	OR	ON	2005/09/30 10:47
S32	2190	S31 and (insulating with resin)	US-PGPUB; USPAT	OR	ON	2005/09/30 10:48
S33	1737	S32 and ((external with (terminal or electrode)) or solder)	US-PGPUB; USPAT	OR	ON	2005/09/30 10:48
S34	20478	S30 and (substrate and chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:47
S35	2289	S34 and (insulating with resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:48
S36	1755	S35 and ((external with (terminal or electrode)) or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:49

S37	550	S36 and ((interconnect or wiring) near pattern)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 11:52
S38	6	S37 and (dispersant with (conduct$3 near particle))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 11:54
S39	20	S37 and (paste with (conduct$3 near particle))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:52
S40	14628	chip near carrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:05
S41	12566	S40 and @ad<"20030313"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:06
S42	325	S41 and (conduct$3 near particle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:07
S43	12643	(chip adj on adj board) or cob	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:06
S44	10912	S43 and @ad<"20030313"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:06
S45	731	S44 and ((dispersant or paste) and conduct$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:08
S46	7549	(257/672,673,678,684,687,780,738, 782,783,784).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/09/30 13:45
S47	6015	S46 and @ad<"20030313"	US-PGPUB; USPAT	OR	ON	2005/09/30 13:45
S48	1670	S47 and (dispersant or paste or (conduct$3 with particle$1))	US-PGPUB; USPAT	OR	ON	2005/09/30 13:45

S49	1155	S48 and resin	US-PGPUB; USPAT	OR	ON	2005/09/30 13:45
S50	997	S49 and ((external adj terminal) or (solder))	US-PGPUB; USPAT	OR	ON	2005/09/30 13:45
S51	798	S50 and (substrate and chip)	US-PGPUB; USPAT	OR	ON	2005/09/30 13:45
S52	200	S51 and (electrode with (top or upper))	US-PGPUB; USPAT	OR	ON	2005/09/30 13:45